



Product Change Notification

Product Change Notification Number: CC101702

Date: May 13, 2010

Title: Module Lead Frame Change from NI Standard material to NXT Material Used for Smart Card Modules for Shipments concerning the Secure Memory Family of Devices

Product Identification:

AT88SC102-09ET-00

Reason for Change:

☐ Design

☐ Manufacturing Location

☒ Processing

☐ Quality/Reliability

☐ Logistics

☐ Material

Change Description:

The thickness of the Nickel and Gold used for plating the lead frame material used in smart card module assembly has been reduced. See Attachment A.

Identification Method to Distinguish Change:

None that can be identified. New lead frame material is undistinguishable from material being used now for smart card modules. Part numbers will remain the same.

Qualification Data:

☒ available

☐ will be available in WW__

☐ not applicable

Samples:

☒ available

☐ will be available in WW__

☐ not applicable

Quantifiable Impact on Quality & Reliability:

None

Proposed First Ship Date*: August 1, 2010

Note: Due to the availability of NI Standard material, NXT material may be required to be used to meet deliveries for some products.

**The Proposed First Ship Date is the forecasted date that a customer may expect to receive changed product. This is determined by the estimated date of inventory depletion on the PCN issue date. This may be affected by fluctuations in supply and demand. Consequently, although customers should be prepared to receive changed product on this date, Atmel will continue to ship pre-changed product until a time in which inventory has been depleted. This may result in pre-changed product being shipped to customers after this forecasted date.*

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Atmel will deem this change accepted unless specific conditions of acceptance are provided in writing within 30 days from the date of this notice. All correspondence must be sent to the Atmel Contact e-mail address listed above.

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Attachment A

STANDARD CONTACT MODULE LEADFRAME MATERIAL THICKNESS
Vs.
NXT CONTACT MODULE LEADFRAME MATERIAL THICKNESS

Table 1

		Thickness Contact Side (uM)		Thickness Bonding Side (uM)	
Ni STANDARD	Nickel	3	+ / - 1	5	+ / - 2
	Gold	0.15	+ / - 0.05	0.30	+ / - 0.10
NXT	Nickel	2	+1 / -0.6	5	+3 / -2
	Gold	0.05	+0.03 / -0.02	0.30	+0.20 / -0.10

Note: Current leadframe used is: Ni Standard. New leadframe to be released: NXT